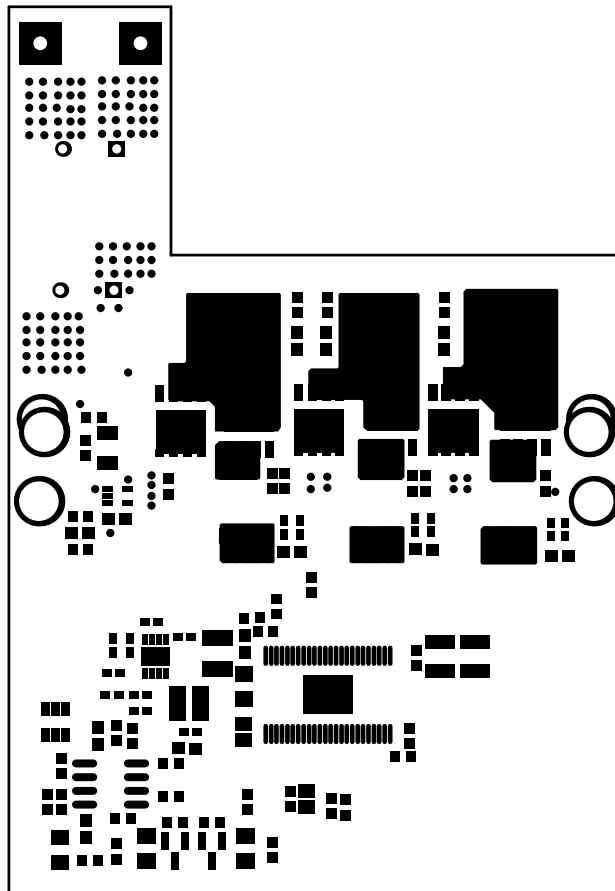
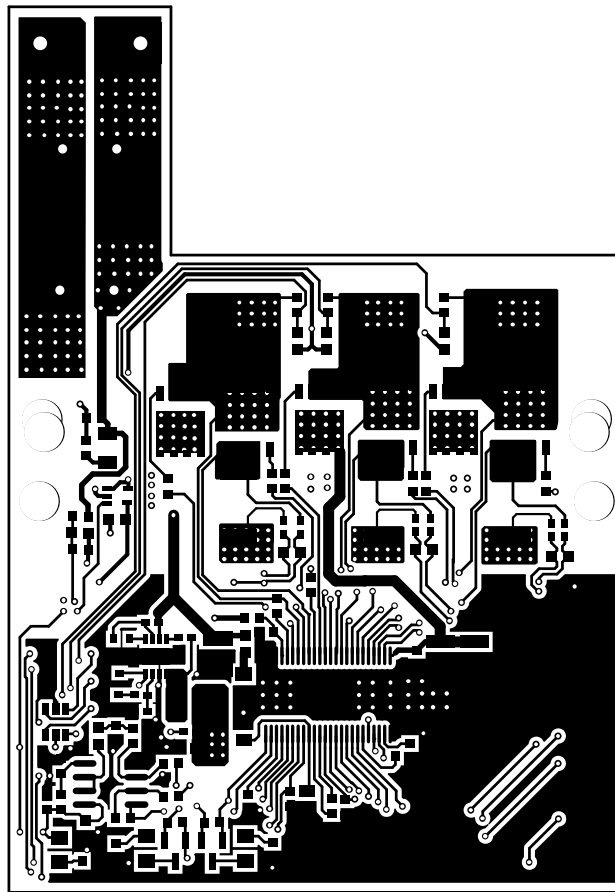


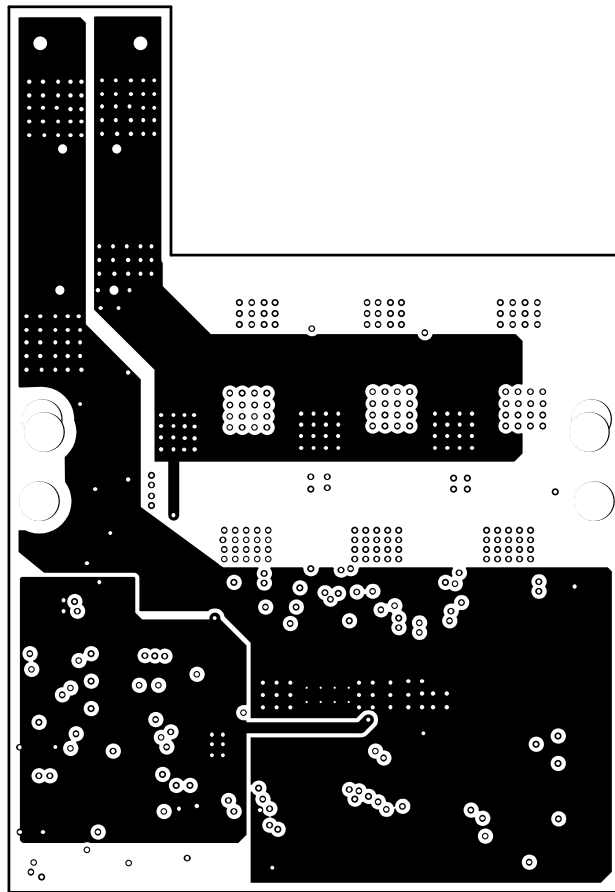
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = TOP OVERLAY			
PLOT NAME = Top Overlay	GENERATED : 10/21/2014 8:00:22 PM	TEXAS INSTRUMENTS	



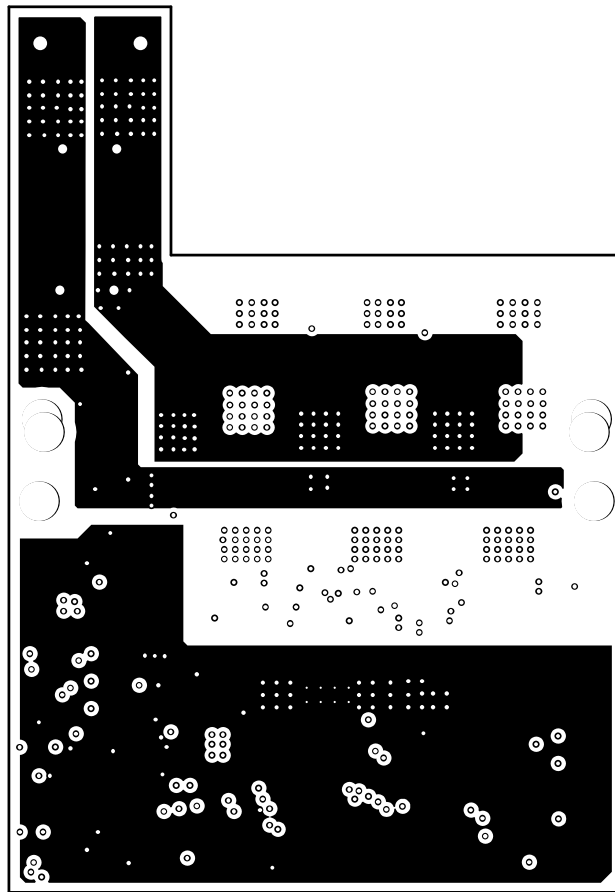
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = SOLDER MASK TOP			
PLOT NAME = Top Solder Mask	GENERATED : 10/21/2014 8:00:22 PM	TEXAS INSTRUMENTS	



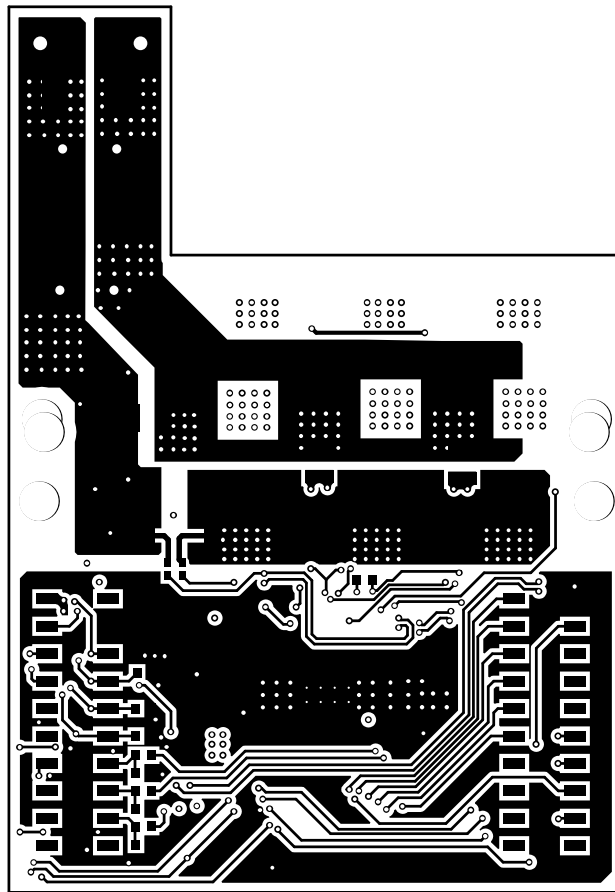
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = TOP_LAYER			
PLOT NAME = Top Layer	GENERATED : 10/21/2014 8:00:23 PM	TEXAS INSTRUMENTS	



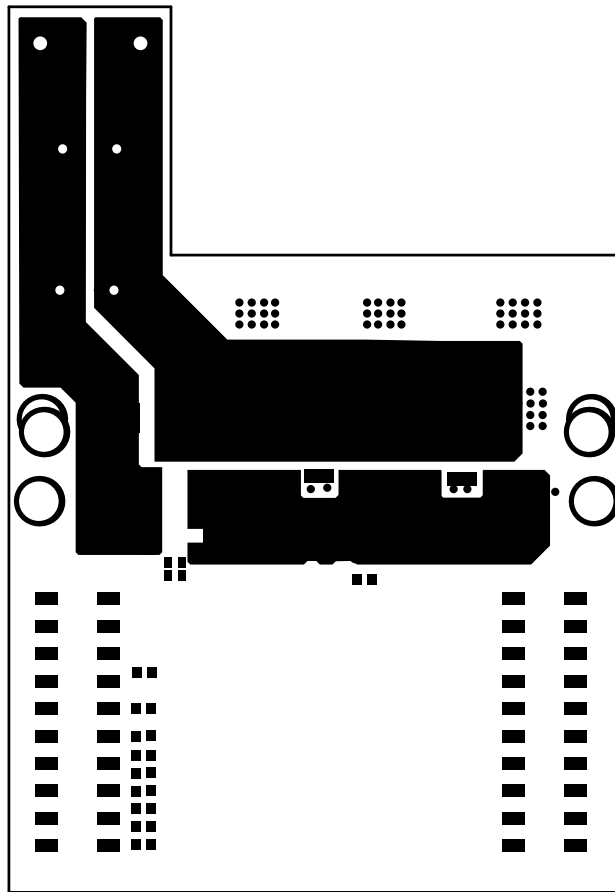
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = LAYER2_POWER PLANE			
PLOT NAME = MidLayer1	GENERATED : 10/21/2014 8:00:24 PM	TEXAS INSTRUMENTS	



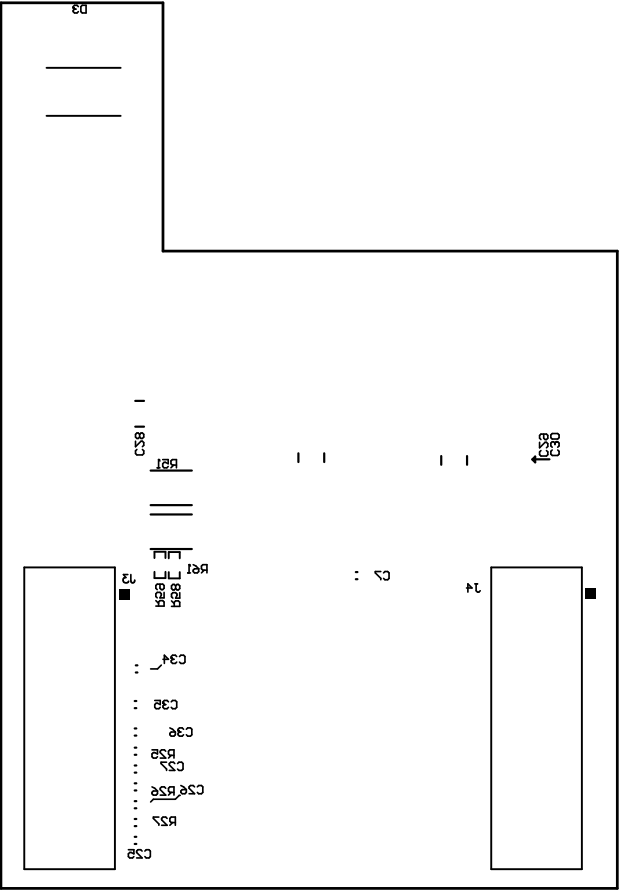
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = LAYER3_GND PLANE			
PLOT NAME = MidLayer2	GENERATED : 10/21/2014 8:00:24 PM	TEXAS INSTRUMENTS	



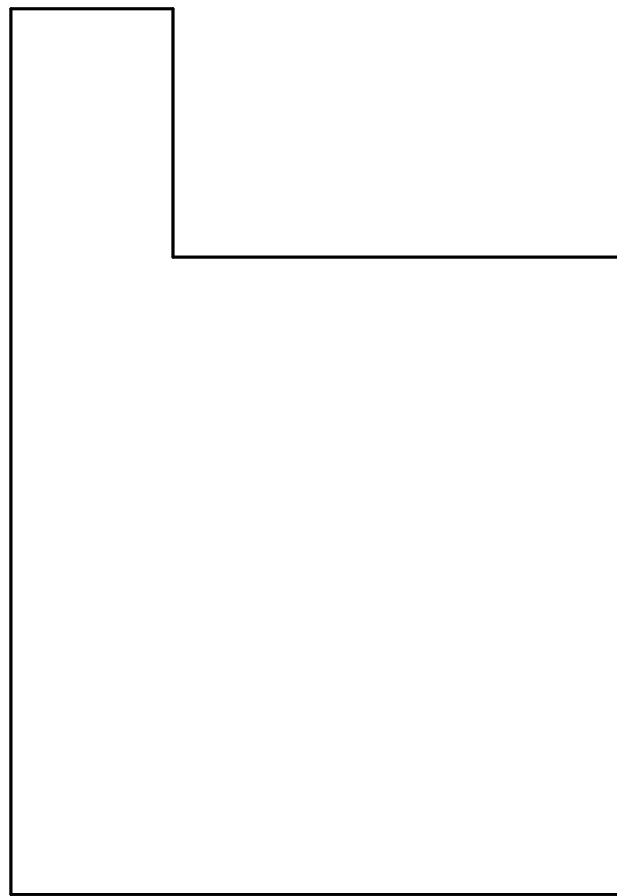
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = BOTTOM LAYER			
PLOT NAME = Bottom Layer	GENERATED : 10/21/2014 8:00:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = SOLDER MASK BOTTOM			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/21/2014 8:00:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = BOTTOM OVERLAY			
PLOT NAME = Bottom Overlay	GENERATED : 10/21/2014 8:00:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00285	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Board Outline	GENERATED : 10/21/2014 8:00:26 PM		TEXAS INSTRUMENTS

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